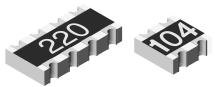
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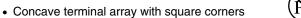


Thick Film Resistor Array



CRA06P Thick Film resistor array is constructed on a high grade ceramic body with concave terminations. A small package enables the design of high density circuits. The single component reduces board space, component counts and assembly costs.

FEATURES





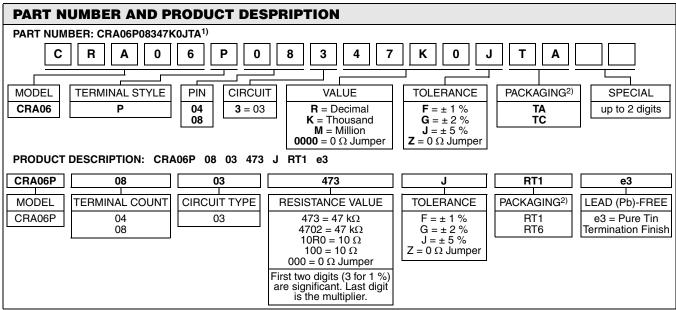
- 4 and 8 terminal package with isolated resistors
- Wide ohmic range: 10R to 1M0
- Lead (Pb)-free solder contacts on Ni barrier layer
- Pure tin plating provides compatibility with lead (Pb)-free and lead containing soldering processes
- Compatible with "Restriction of the use of Hazardous Substances" (RoHS) directive 2002/95/EC (issue 2004)

STANDARD ELECTRICAL SPECIFICATIONS								
MODEL	CIRCUIT	POWER RATING P _{70 °C} W	LIMITING ELEMENT VOLTAGE MAX. V_{\cong}	TEMPERATURE COEFFICIENT ppm/K	TOLERANCE %	$\begin{array}{c} \textbf{RESISTANCE} \\ \textbf{RANGE} \\ \Omega \end{array}$	E-SERIES	
CRA06P	03	0.063	50	± 100 ± 200	± 1 ± 2; ± 5	10R - 1M0	24 + 96 24	
		Zero-Ohm-Resistor: $R_{\text{max}} = 50 \text{ m}\Omega$, $I_{\text{max}} = 1 \text{ A}$						

TECHNICAL SPECIFICATIONS						
PARAMETER	UNIT	CRA06P 03 CIRCUIT				
Rated Dissipation at 70 °C ²⁾	W per element	0.063				
Limiting Element Voltage ¹⁾	V≅	50				
Insulation Voltage (1 min)	V _{dc/ac peak}	100				
Category Temperature Range	°C	- 55/+ 125 (+ 155)				
Insulation Resistance	Ω	> 10 ⁹				

Notes

- 1. Rated voltage: $\sqrt{P \times R}$
- The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat flow support of the printed-circuit board (thermal resistance). The rated dissipation applies only if the permitted film temperature of 155 °C is not exceeded.



Notes

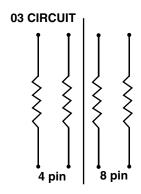
- 1. Preferred way for ordering products is by use of the PART NUMBER.
- 2. Please refer to the table PACKAGING, see next page.

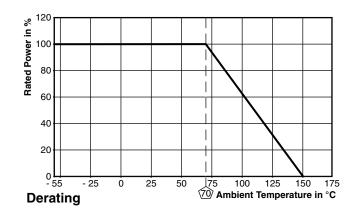


Thick Film Resistor Array

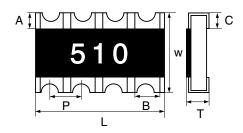
PACKAGING							
	TAPE WIDTH	DIAMETER	PITCH	DIFOEC	PACKAGING CODE PAPER TAPE		
MODEL				PIECES /REEL			
					PART NUMBER	PRODUCT DESCRIPTION	
CRA06P 8 mm	9 mm	180 mm/7"	4 mm	5000	TA	RT1	
	0 111111	330 mm/13"	4 mm	20 000	TC	RT6	

CIRCUIT

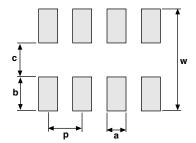




DIMENSIONS



PIN	DIMENSIONS [in millimeters]								
NO#	L	Α	В	C	Р	Т	W		
4	1.60	0.30	0.40	0.40	0.80	0.60	1.60		
8	3.20	0.30	0.40	0.40	0.80	0.60	1.60		
Tol	± 0.20	± 0.20	± 0.15	± 0.20		± 0.10	± 0.15		



SOLDER PAD DIMENSIONS [in millimeters]						
	С	w	р	а	b	
WAVE	0.8	2.6	0.8	0.4	0.9	

Thick Film Resistor Array



TEST PROCEDURES AND REQUIREMENTS EN 60115-1						
(clause)	CONDITIONS OF TEST	STABILITY CLASS 1 OR BETTER	STABILITY CLASS 2 OR BETTER			
	stability for product types: CRA06P	10 Ω to 1 MΩ	10 Ω to 1 MΩ			
Resistance (4.5)	-	± 1 %	± 2 %; ± 5 %			
Temperature coefficient (4.8.4.2)	20/- 55/20 °C and 20/125/20 °C	± 100 ppm/K	± 200 ppm/K			
Overload (4.13)	$U = 2.5 \times (P_{70} \times R)^{1/2}$ $\leq 2 \times U_{\text{max}}; 0.5 \text{ s}$	± (0.25 % R + 0.05 Ω)	± (0.5 % R + 0.05 Ω)			
Solderability (4.17.5) ²⁾	Aging 4 h at 155 °C, dryheat Solder bath method; 235 °C; 2 s Visual examination	Good tinning (≥ 95 % covered) no visible damage				
Resistance to soldering heat (4.18.2)	Solder bath method; (260 ± 5) °C; (10 ± 1) s	± (0.25 % R + 0.05 Ω)	± (0.5 % R + 0.05 Ω)			
Rapid change of temperature (4.19)	30 min. at LCT = - 55 °C; 30 min. at UCT = 125 °C; 5 cycles	± (0.25 % R + 0.05 Ω)	± (0.5 % R + 0.05 Ω)			
Damp heat, steady state (4.24)	(40 ± 2) °C; 56 days; (93 ± 3) % RH	± (1 % R + 0.05 Ω)	± (2 % R + 0.1 Ω)			
Climatic sequence (4.23)	16 h at UCT = 125 °C; 1 cycle at 55 °C; 2 h at LCT = -55 °C; 1 h/1 kPa at 15 °C to 35 °C; 5 cycles at 55 °C U = (P ₇₀ x R) ^{1/2} U = U _{max} ; whichever is less severe	± (1 % R + 0.05 Ω)	± (2 % R + 0.1 Ω)			
Endurance at 70 °C (4.25.1)	$U = (P_{70} \times R)^{1/2}$ $U = U_{\text{max}}$; whichever is less severe 1.5 h on; 0.5 h off; 70 °C; 1000 h	± (1 % R + 0.05 Ω)	± (2 % R + 0.1 Ω)			
Extended endurance (4.25.1.8)	Duration extended to 8000 hours	± (2 % R + 0.1 Ω)	± (4 % R + 0.1 Ω)			
Endurance at upper category temperature (4.25.3)	UCT = 125 °C; 1000 h	± (1 % R + 0.05 Ω)	± (2 % R + 0.1 Ω)			

Notes

- 1. Figures are given for a single element.
- $2. \ \ Solderability is specified for 2 years after production or requalification. Permitted storage time is 20 years.$

APPLICABLE SPECIFICATIONS

EN 60115-1 Generic Specification
 EN 140400 Sectional Specification
 EN 140401-802 Detail Specification

• IEC 60068-2-X Variety of environmental test procedures

• EIA 481 Packaging of SMD components

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Legal Disclaimer Notice



Vishay

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